

# USER MANUAL

**MP P/N: CMWX1ZZABZ**

**Sample P/N: CMWX1ZZABZ-TEMP**

**For LoRa™**

## Revision History

| Revision Code | Date          | Description   | Comments |
|---------------|---------------|---|----------|
| A             | June 8, 2016  | Initial Draft   |          |
| B             | July 1, 2016  | Updated height and package info   |          |
| C             | July 30, 2016 | Revised some formats and $\Delta$ RF_OPH_V test condition from 2.4-3.7V to 2.2-3.6V. Updated some electronic Characteristics. Added the recommended land pattern. |          |
| D             | Aug 29, 2016  | Updated the RF performance, Electrical Characteristics and power up sequence.   |          |
| E             | Oct 11, 2016  | Added FCC and IC statements.  |          |
| F             | Aug 20, 2018  | Added additional antenna info.  |          |

**TABLE OF CONTENTS**

|  |    |
|--|----|
| 1. Features .....  | 4  |
| 2. Part Number .....                                     | 4  |
| 3. Block Diagram .....                                   | 4  |
| 4. Dimensions, Marking and Terminal Configurations ..... | 5  |
| 5. Label Information .....                               | 8  |
| 6. Absolute Maximum Ratings .....                        | 8  |
| 7. Operating Condition .....                             | 8  |
| 8. Electrical Characteristics .....                      | 9  |
| 9. Power Sequences .....                                 | 10 |
| 10. Recommend Land Pattern .....                         | 11 |
| 11. Reference circuit .....                              | 12 |
| 12. Tape and Reel packing .....                          | 13 |
| 13. Notice .....   | 16 |
| 14. Regulatory Statements .....                          | 18 |

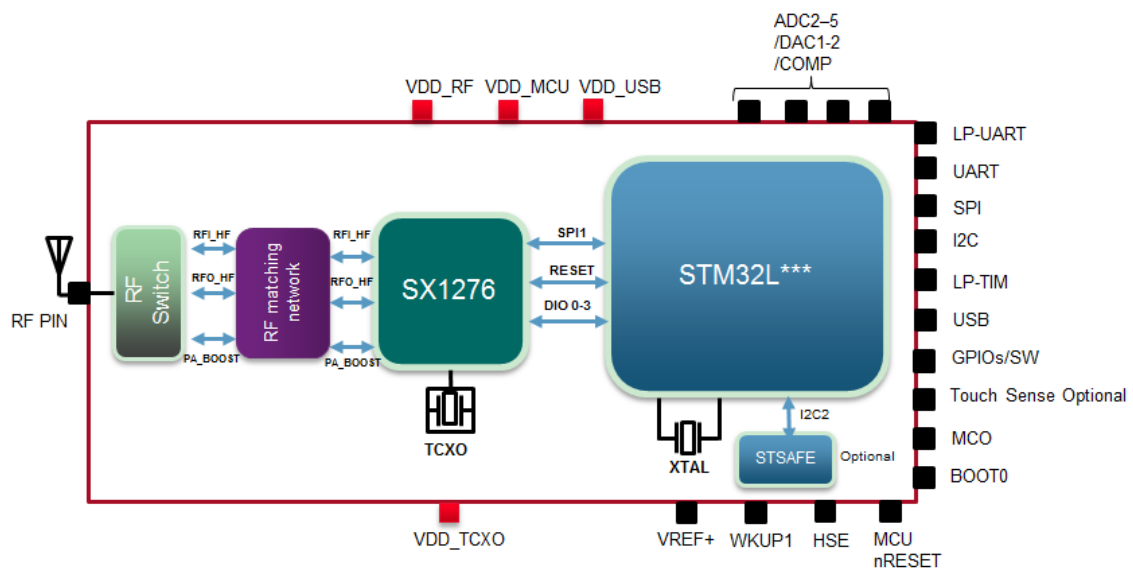
## 1. Features

|                       |  |
|-----------------------|--|
| Interfaces            | : I2C, UART, USB, SPI  |
| Main ICs              | : STM32L082, SX1276  |
| Reference Clocks      | : Integrated 32MHz clock (TCXO with frequency error= $\pm 2$ ppm)<br>and 32.768KHz clock (frequency error= $\pm 20$ ppm) |
| Supported Frequencies | : 868 MHz, 915 MHz   |
| Module Size           | : 12.5 mm x 11.6 mm x 1.76 mm (Max)  |
| Package               | : Metal Shield can   |
| RoHS                  | : This module is compliant with the RoHS directive   |

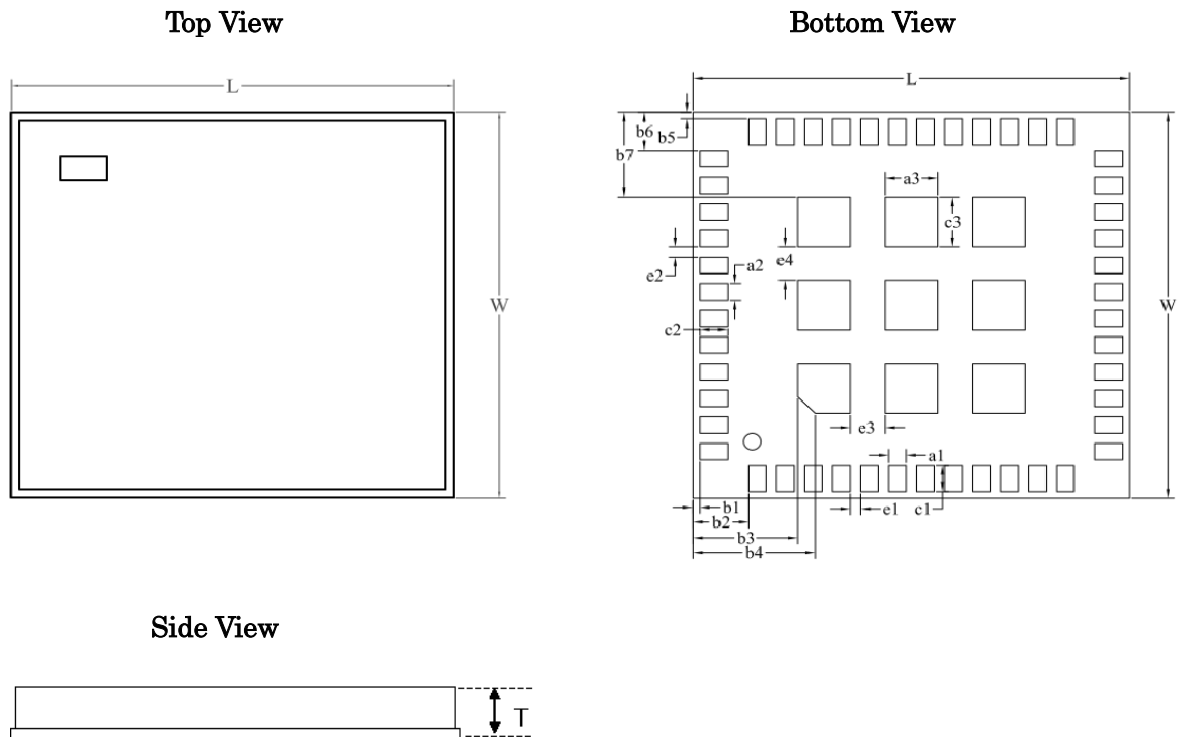
## 2. Part Number

| Ordering Part Number | Description        |
|----------------------|--------------------|
| CMWX1ZZABZ           | MP P/N             |
| CMWX1ZZABZ-TEMP      | Engineering sample |

## 3. Block Diagram



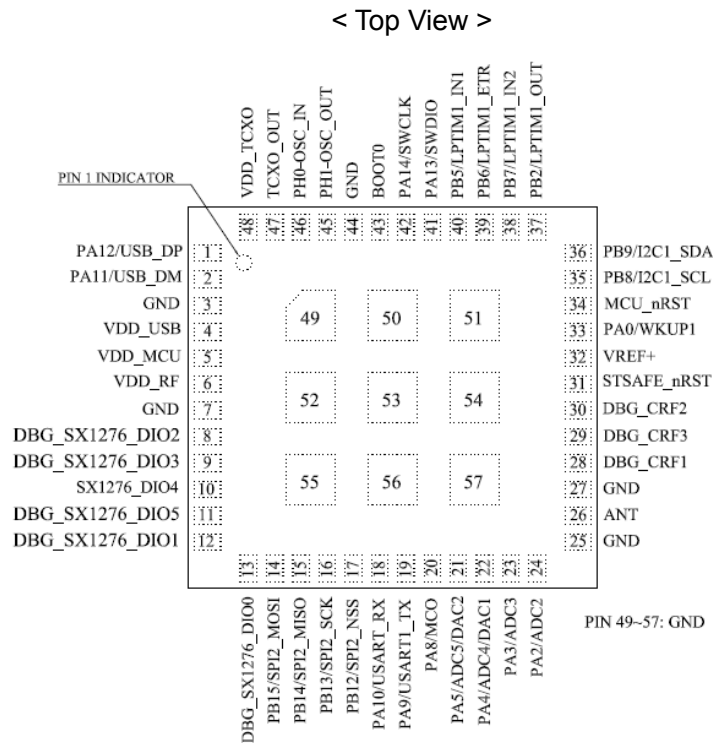
**4. Dimensions, Marking and Terminal Configurations**



**Table 1** Dimension (Unit: mm)

| Mark      | Dimension | Mark      | Dimension | Mark      | Dimension |
|-----------|-----------|-----------|-----------|-----------|-----------|
| <b>L</b>  | 12.5±0.20 | <b>W</b>  | 11.6±0.20 | <b>T</b>  | 1.76 max  |
| <b>a1</b> | 0.50±0.10 | <b>a2</b> | 0.50±0.10 | <b>a3</b> | 1.50±0.10 |
| <b>b1</b> | 0.20±0.15 | <b>b2</b> | 1.60±0.15 | <b>b3</b> | 3.00±0.15 |
| <b>b4</b> | 3.50±0.15 | <b>b5</b> | 0.20±0.15 | <b>b6</b> | 1.15±0.15 |
| <b>b7</b> | 2.55±0.15 | <b>c1</b> | 0.80±0.10 | <b>c2</b> | 0.80±0.10 |
| <b>c3</b> | 1.50±0.10 | <b>e1</b> | 0.30±0.10 | <b>e2</b> | 0.30±0.10 |
| <b>e3</b> | 1.00±0.10 | <b>e4</b> | 1.00±0.10 |           |           |

Terminal Configurations



**Table 2** Terminal Configurations

| Pin NO. | Terminal Name   | Type   | Connection to IC terminal | Description                 |
|---------|-----------------|--------|---------------------------|-----------------------------|
| 1       | PA12/USB_DP     | I/O    | STM32L082_PA12            | GPIO Mode:PA12<br>USB_DP    |
| 2       | PA11/USB_DM     | I/O    | STM32L082_PA11            | GPIO Mode:PA11<br>USB_DM    |
| 3       | GND             | Ground | -                         | Ground                      |
| 4       | VDD_USB         | Power  | -                         | Power supply for USB        |
| 5       | VDD_MCU         | Power  | -                         | Power supply for MCU        |
| 6       | VDD_RF          | Power  | -                         | Power supply for RF IC      |
| 7       | GND             | Ground | -                         | Ground                      |
| 8       | DBG_SX1276_DIO2 | I/O    | SX1276_DIO2               | Debug pin for SX1276        |
| 9       | DBG_SX1276_DIO3 | I/O    | SX1276_DIO3               | Debug pin for SX1276        |
| 10      | SX1276_DIO4     | I/O    | SX1276_DIO4               | SX1276 DIO4                 |
| 11      | DBG_SX1276_DIO5 | I/O    | SX1276_DIO5               | Debug pin for SX1276        |
| 12      | DBG_SX1276_DIO1 | I/O    | SX1276_DIO1               | Debug pin for SX1276        |
| 13      | DBG_SX1276_DIO0 | I/O    | SX1276_DIO0               | Debug pin for SX1276        |
| 14      | PB15/SPI2_MOSI  | I/O    | STM32L082_PB15            | GPIO Mode:PB15<br>SPI2_MOSI |
| 15      | PB14/SPI2_MISO  | I/O    | STM32L082_PB14            | GPIO Mode:PB14<br>SPI2_MISO |
| 16      | PB13/SPI2_SCK   | I/O    | STM32L082_PB13            | GPIO Mode:PB13<br>SPI2_SCK  |
| 17      | PB12/SPI2_NSS   | I/O    | STM32L082_PB12            | GPIO Mode:PB12<br>SPI2_NSS  |
| 18      | PA10/USART1_RX  | I/O    | STM32L082_PA10            | GPIO Mode:PA10<br>USART1_RX |

|    |                |        |                |   |
|----|----------------|--------|----------------|---|
| 19 | PA9/USART1_TX  | I/O    | STM32L082_PA9  | GPIO Mode:PA9<br>USART1_TX                        |
| 20 | PA8/MCO        | I/O    | STM32L082_PA8  | GPIO Mode:PA8<br>MCO                              |
| 21 | PA5/ADC5/DAC2  | I/O    | STM32L082_PA5  | GPIO Mode:PA5<br>COMP2_INM<br>ADC_IN5<br>DAC_OUT2 |
| 22 | PA4/ADC4/DAC1  | I/O    | STM32L082_PA4  | GPIO Mode:PA4<br>COMP2_INM<br>ADC_IN4<br>DAC_OUT1 |
| 23 | PA3/ADC3       | I/O    | STM32L082_PA3  | GPIO Mode:PA3<br>COMP2_INP<br>ADC_IN3             |
| 24 | PA2/ADC2       | I/O    | STM32L082_PA2  | GPIO Mode:PA2<br>COMP2_OUT<br>ADC_IN2             |
| 25 | GND            | Ground | -              | Ground  |
| 26 | ANT            | A,I/O  | -              | Transmit / Receive Antenna                        |
| 27 | GND            | Ground | -              | Ground  |
| 28 | DBG_CRF1       | I/O    | STM32L082_PA1  | Debug pin   |
| 29 | DBG_CRF3       | I/O    | STM32L082_PC1  | Debug pin   |
| 30 | DBG_CRF2       | I/O    | STM32L082_PC2  | Debug pin   |
| 31 | STSAFE_nRST    | I      | -              | Reset for Security IC                             |
| 32 | VREF+          | Power  | -              | Reference Voltage For ADC and DAC                 |
| 33 | PA0/WKUP1      | I/O    | STM32L082_PA0  | GPIO Mode:PA0<br>COMP2_OUT<br>ADC_IN2             |
| 34 | MCU_nRST       | I      | STM32L082_PD5  | NRST  |
| 35 | PB8/I2C1_SCL   | I/O    | STM32L082_PB8  | GPIO Mode:PB8<br>I2C mode: SCL                    |
| 36 | PB9/I2C1_SDA   | I/O    | STM32L082_PB9  | GPIO Mode: PB9<br>I2C mode: SDA                   |
| 37 | PB2/LPTIM1_OUT | I/O    | STM32L082_PB2  | GPIO Mode:PB2<br>LPTIM1_OUT                       |
| 38 | PB7/LPTIM1_IN2 | I/O    | STM32L082_PB7  | GPIO Mode:PB7<br>LPTIM1_IN2                       |
| 39 | PB6/LPTIM1_ETR | I/O    | STM32L082_PB6  | GPIO Mode:PB6<br>LPTIM1_ETR                       |
| 40 | PB5/LPTIM1_IN1 | I/O    | STM32L082_PB5  | GPIO Mode:PB5<br>LPTIM1_IN1                       |
| 41 | PA13/SWDIO     | I/O    | STM32L082_PA13 | GPIO Mode:PA13<br>SWDIO<br>LPUART1_RX             |
| 42 | PA14/SWCLK     | I/O    | STM32L082_PA14 | GPIO Mode:PA14<br>SWCLK<br>LPUART1_TX             |
| 43 | BOOT0          | I      | STM32L082_PA5  | Boot Option                                       |

|       |             |        |               |   |
|-------|-------------|--------|---------------|---|
| 44    | GND         | Ground | -             | -   |
| 45    | PH1-OSC_OUT | I/O    | STM32L082_PH1 | GPIO Mode:PH1<br>High-speed external clock OSC output |
| 46    | PH0-OSC_IN  | I/O    | STM32L082_PH0 | GPIO Mode:PH0<br>High-speed external clock OSC input  |
| 47    | TCXO_OUT    | O      | -             | Internal TCXO output                                  |
| 48    | VDD_TCXO    | Power  | -             | Power supply for the TCXO IC                          |
| 49~57 | GND         | Ground | -             | Ground  |

Note: GPIO pins are to be left OPEN if not used.

## 5. Label Information

TBD

## 6. Absolute Maximum Ratings

Table 3 Maximum ratings

| Parameters          |                           | Min  | Typ | Max                      | Unit |
|---------------------|---------------------------|------|-----|--------------------------|------|
| Storage Temperature |                           | -40  | 25  | +90                      | degC |
| Input RF Level      |                           | -    | -   | 10                       | dBm  |
| Supply Voltage      | VDD_USB                   | -0.3 | -   | 3.9                      | V    |
|                     | VDD_MCU, VDD_RF, VDD_TCXO | -0.3 | -   | 3.9                      | V    |
|                     | VREF+                     | -0.3 | -   | V <sub>DD_MCU</sub> +0.4 | V    |

## 7. Operating Condition

Table 4 Operating specification

| Parameters            |   | Min                     | Typ                 | Max                     | Unit |
|-----------------------|---|-------------------------|---------------------|-------------------------|------|
| Operating Temperature |   | -40                     | 25                  | +85                     | degC |
| Supply Voltage        | VDD_USB (USB peripheral used) <sup>(1)</sup>    | 3.0                     | -                   | 3.6                     | V    |
|                       | VDD_USB(USB peripheral not used) <sup>(1)</sup> | V <sub>DD_MCU_min</sub> | V <sub>DD_MCU</sub> | V <sub>DD_MCU_max</sub> | V    |
|                       | VDD_MCU, VDD_RF, VDD_TCXO                       | 2.2 <sup>(3)</sup>      | -                   | 3.6                     | V    |
|                       | VREF+ <sup>(2)</sup>                            | 1.8                     | -                   | V <sub>DD_MCU</sub>     | V    |

(1) VDD\_USB must respect the following conditions:

- When VDD\_MCU is powered on (VDD\_MCU < VDD\_MCU\_min), VDD\_USB should be always lower than VDD\_MCU.
- When VDD\_MCU is powered down (VDD\_MCU < VDD\_MCU\_min), VDD\_USB should be always lower than VDD\_MCU.
- In operating mode, VDD\_USB could be lower or higher than VDD\_MCU.
- If the USB is not used, VDD\_USB must be tied to VDD\_MCU to be able to use PA11 and PA12 as standard I/Os.

(2) VREF+ is used to ensure a better accuracy on low-voltage inputs and outputs of ADC and DAC. Detailed information is on the STM32L082\*\*\* datasheet and user guider.

(3) When module is on +20dBm operation, the supply of the voltage should be set from 2.4V to 3.6V.



## 8. Electrical Characteristics

### 8.1 FSK/OOK Transceiver Specification

Conditions:

Supply voltage VDD=3.3 V, temperature = 25 °C, FXOSC = 32 MHz, FRF =868/915 MHz , 2-level FSK modulation without pre-filtering, FDA = 5 kHz, Bit Rate = 4.8 kb/s and terminated in a matched 50 Ohm impedance, shared Rx and Tx path matching, unless otherwise specified.

#### FSK/OOK Receiver Specification

| Symbol   | Description                    | Conditions                 | Min. | Typ    | Max | Unit |
|----------|--------------------------------|----------------------------|------|--------|-----|------|
| RFS_F_HF | LnaBoost is turned on          | FDA = 5 kHz, BR = 4.8 kb/s |      | -117.5 |     | dBm  |
| IDDR     | Supply current in Receive mode | LnaBoost Off, band 1       |      | 22     |     | mA   |
|          |                                | LnaBoost On, band 1        |      | 23     |     | mA   |

#### FSK/OOK Transmitter Specification

| Symbol    | Description  | Conditions                    | Min. | Typ    | Max | Unit |
|-----------|--|-------------------------------|------|--------|-----|------|
| RF_OP     | RF output power in 50 ohms on RFO pin ( High efficiency PA)      | Programmable with steps       | Max  | 14     |     | dBm  |
|           |  |                               | Min  | -5     |     | dBm  |
| RF_OPH    | RF output power in 50 ohms on PA_BOOST pin( Regulated PA)        | Programmable with 1dB steps   | Max  | 18.5   |     | dBm  |
|           |  |                               | Min  | 2      |     | dBm  |
| ΔRF_OPH_V | RF output power stability on PA_BOOST pin versus voltage supply. | VDD = 2.2 V to 3.6 V          |      | +/-1   |     | dB   |
| ΔRF_T     | RF output power stability versus temperature on PA_BOOST pin.    | From T = -40 °C to +85 °C     |      | +/-1.5 |     | dB   |
| IDDT      | Supply current in Transmit mode with impedance matching          | RFOP = +20 dBm, on PA_BOOST   |      | 128    |     | mA   |
|           |  | RFOP = +17 dBm, on PA_BOOST   |      | 106    |     | mA   |
|           |  | RFOP = +14 dBm, on RFO_HF pin |      | 47     |     | mA   |
|           |  | RFOP = + 7 dBm, on RFO_HF pin |      | 34     |     | mA   |

### 8.2 LoRa Transceiver Specification

Conditions:

The table below gives the electrical specifications for the transceiver operating with LoRa™ modulation. Following conditions apply unless otherwise specified: Supply voltage = 3.3 V, Temperature = 25° C, FXOSC = 32 MHz, Error Correction Code (EC) = 4/5, Packet Error Rate (PER)= 1%, CRC on payload enabled, Payload length = 10 bytes.

With matched impedances

#### LoRa Receiver Specification

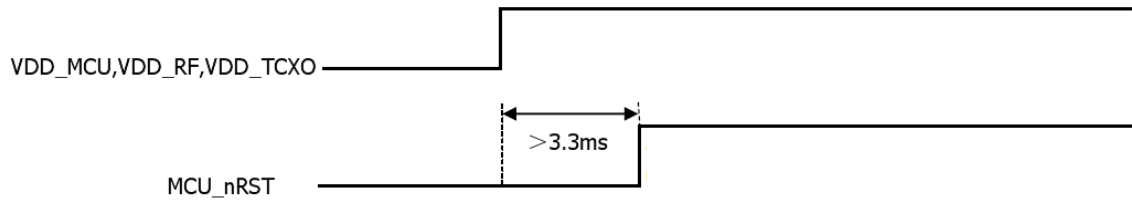
| Symbol      | Description   | Conditions           | Min. | Typ    | Max | Unit |
|-------------|---|----------------------|------|--------|-----|------|
| IDDR_L      | Supply current in receiver LoRa mode, LnaBoost off  | Band 1, BW = 125 kHz |      | 21.5   |     | mA   |
|             |   | Band 1, BW = 250 kHz |      | 22.2   |     | mA   |
|             |   | Band 1, BW = 500 kHz |      | 23.6   |     | mA   |
| RFS_L125_HF | RF sensitivity, Long-Range Mode, highest LNA gain, LnaBoost for Band1, using split Rx/Tx path 125 kHz bandwidth | SF = 6               |      | -117.5 |     | dBm  |
|             |   | SF = 7               |      | -122.5 |     | dBm  |
|             |   | SF = 8               |      | -125.5 |     | dBm  |
|             |   | SF = 9               |      | -128.5 |     | dBm  |
|             |   | SF = 10              |      | -131.0 |     | dBm  |
|             |   | SF = 12              |      | -135.5 |     | dBm  |
| RFS_L250_HF | RF sensitivity, Long-Range Mode, highest LNA gain, LnaBoost for Band1, using split Rx/Tx path 250 kHz bandwidth | SF = 6               |      | -114.0 |     | dBm  |
|             |   | SF = 7               |      | -119.0 |     | dBm  |
|             |   | SF = 8               |      | -122.0 |     | dBm  |
|             |   | SF = 9               |      | -125.0 |     | dBm  |
|             |   | SF = 10              |      | -127.5 |     | dBm  |
|             |   | SF = 12              |      | -133.0 |     | dBm  |

**LoRa Transmitter Specification**

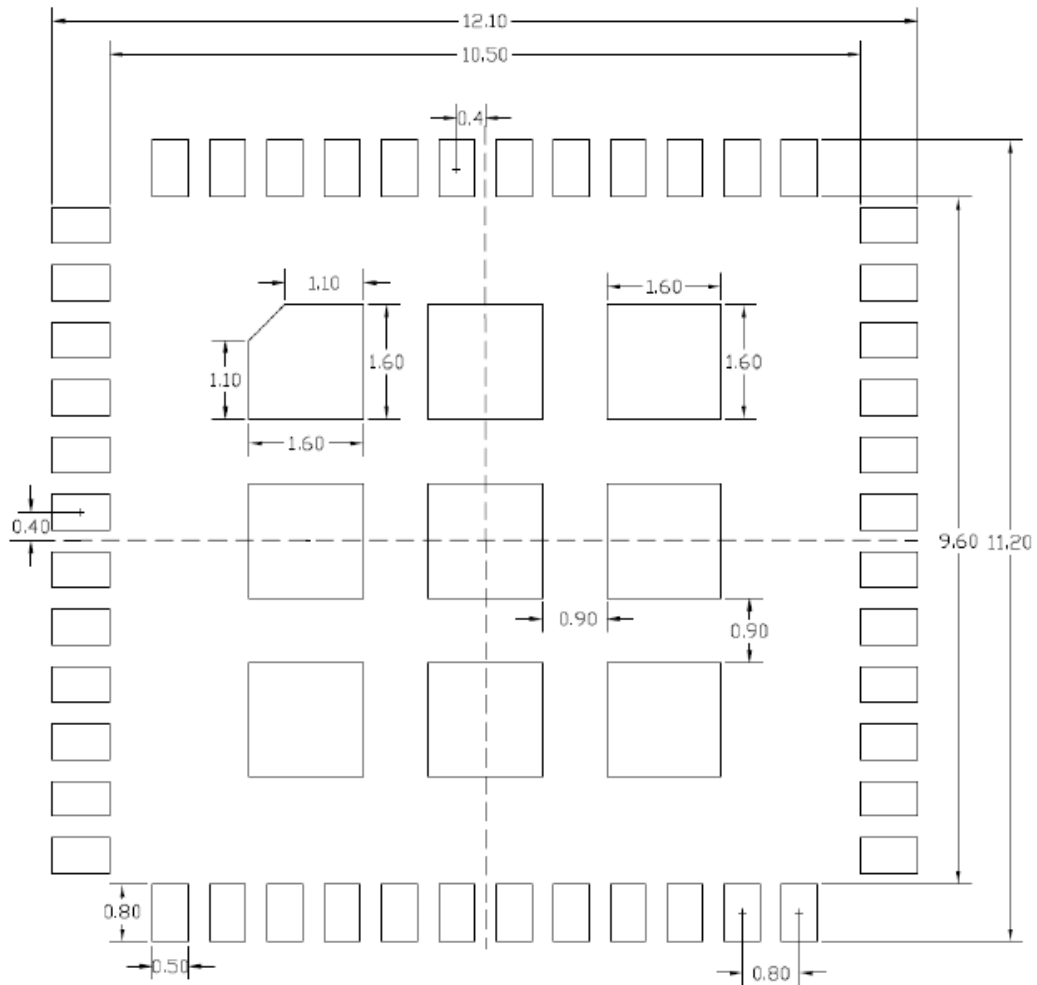
| Symbol   | Description                        | Conditions                                  | Min. | Typ | Max | Unit |
|----------|------------------------------------|---|------|-----|-----|------|
| IDDT_L   | Supply current in transmitter mode | RFOP setting = 14 dBm                       |      | 47  |     | mA   |
|          |                                    | RFOP setting = 10 dBm                       |      | 36  |     | mA   |
| IDDT_H_L | Supply current in transmitter mode | Using PA_BOOST pin<br>RFOP setting = 20 dBm |      | 128 |     | mA   |

**9. Power Sequences**

**9.1 Power Up Sequence**



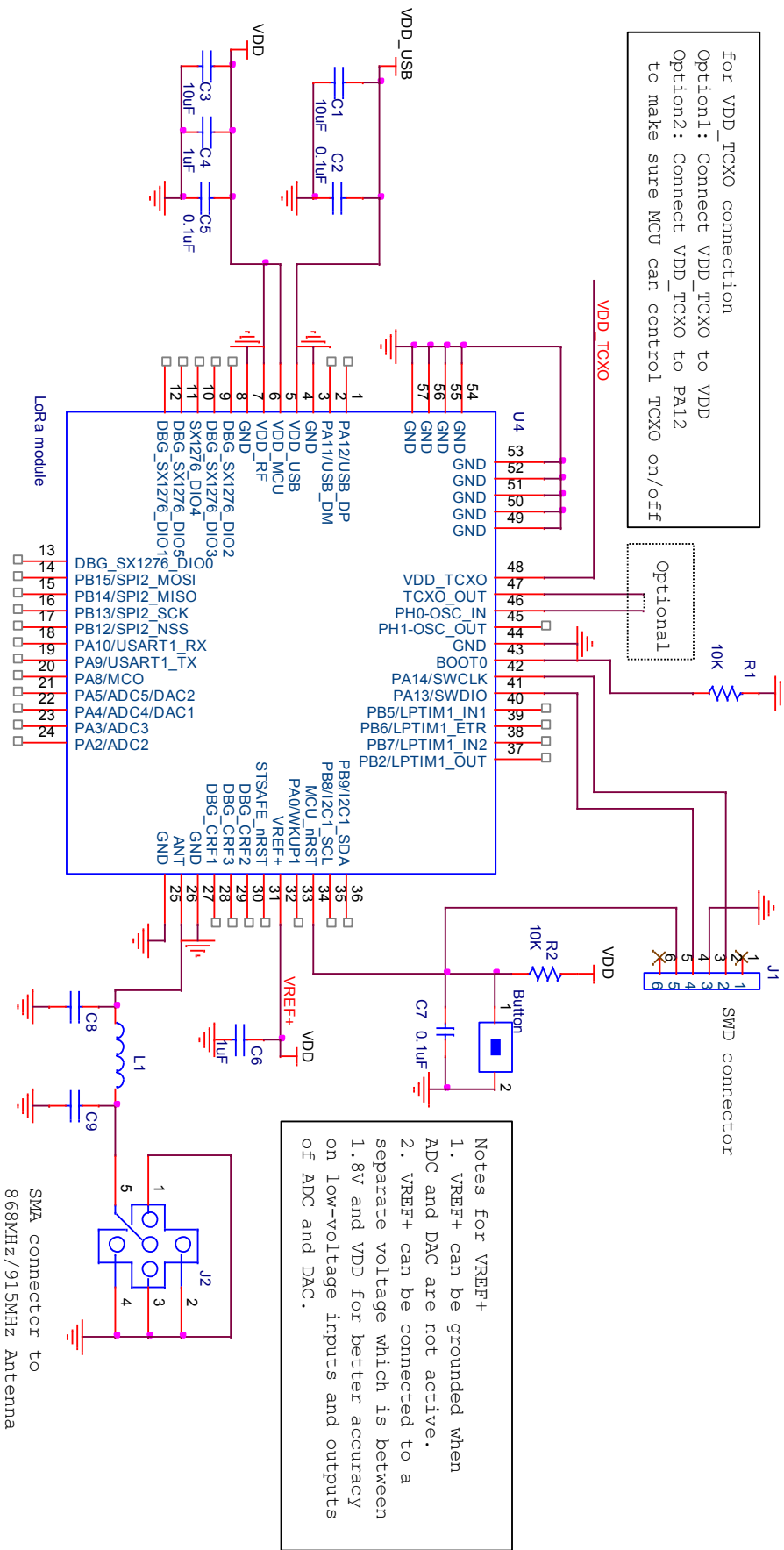
**10. Recommend Land Pattern**



**NOTES:**

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSE ONLY.  
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S  
MANUFACTURING GUIDELINES ARE MET.
3. THERMAL VIAS IN THE LAND PATTERN OF THE EXPOSED PAD SHALL BE CONNECTED  
TO A SYSTEM GROUND PLANE. FAILURE TO DO SO MAY COMPROMISE THE THERMAL  
AND/OR FUNCTIONAL PERFORMANCE OF THE DIVICE.
4. SQUARE PACKAGE-DIMENSIOND APPLY IN BOTH "X" AND "Y" DIRECTIONS.

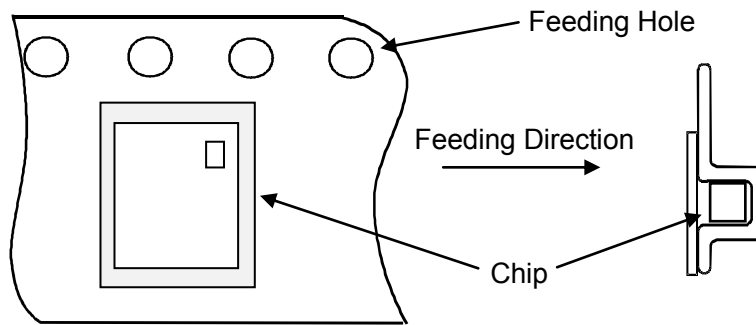
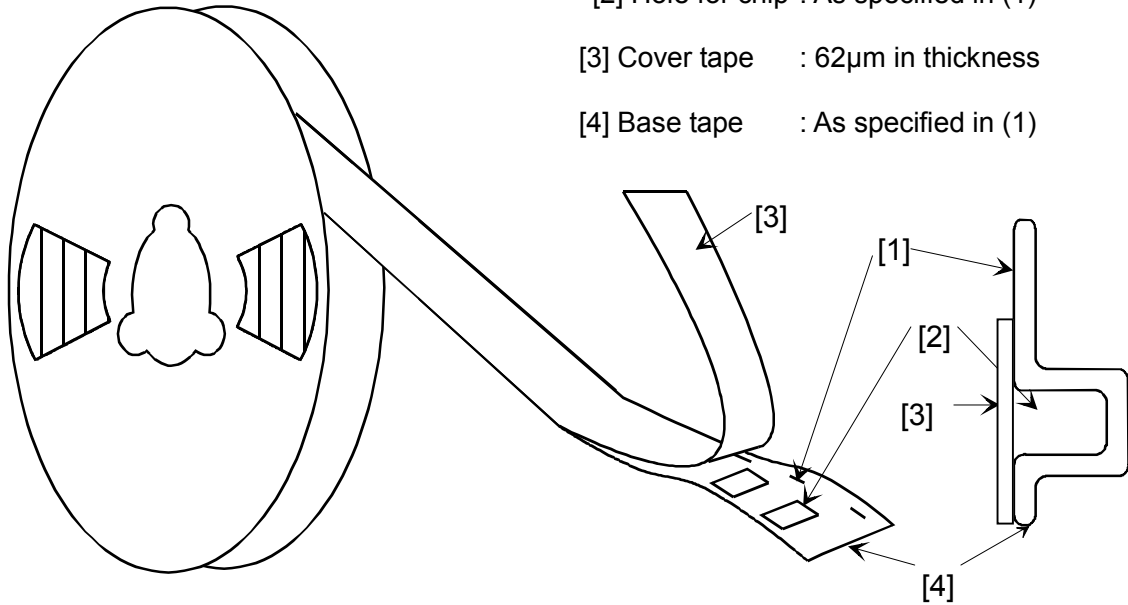
**11. Reference circuit**



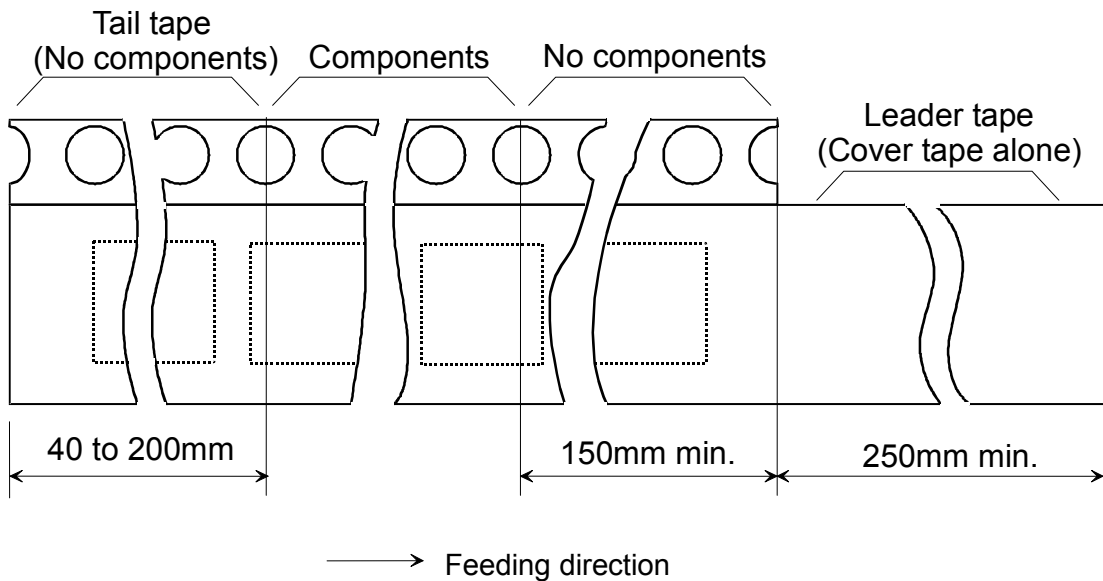


**12.3 Taping Diagrams**

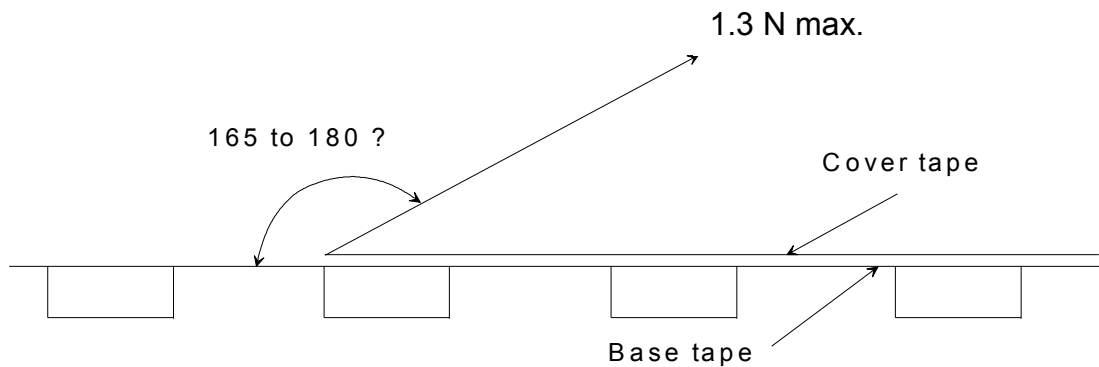
- [1] Feeding Hole : As specified in (1)
- [2] Hole for chip : As specified in (1)
- [3] Cover tape : 62μm in thickness
- [4] Base tape : As specified in (1)



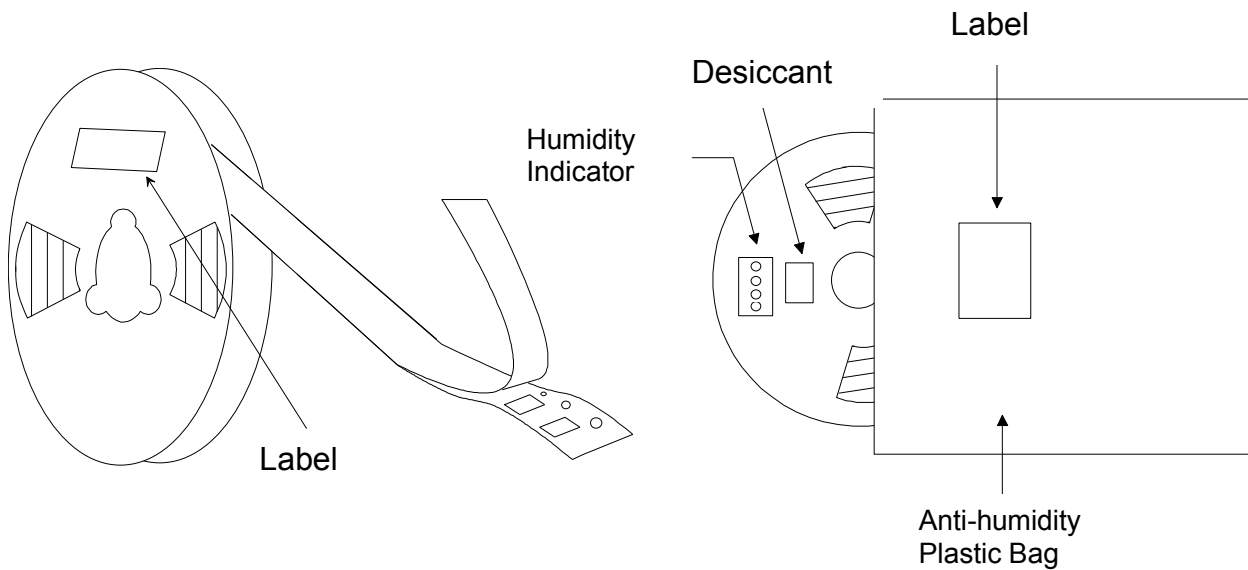
**12.4 Leader and Tail tape**



- The tape for chips are wound clockwise, the feeding holes to the right side as the tape is pulled toward the user.
- The cover tape and base tape are not adhered at no components area for 250mm min.
- Tear off strength against pulling of cover tape : 5N min.
- Packaging unit : 1000 pcs/ reel
- Material
  - Base tape : Plastic
  - Reel : Plastic
  - Cover tape, cavity tape and reel are made the anti-static processing.
- Peeling of force: 1.3N max. in the direction of peeling as shown below.



- Packaging (Humidity proof Packing)



Tape and reel must be sealed with the anti-humidity plastic bag. The bag contains the desiccant and the humidity indicator.

## **13. Notice**

### **13.1 Storage Conditions**

Please use this product within 6month after receipt.

- The product shall be stored without opening the packing under the ambient temperature from 5 to 35 °C and humidity from 20 ~ 70 %RH.

(Packing materials, in particular, may be deformed at the temperature over 40 °C)

- The product left more than 6months after reception, it needs to be confirmed the solderbility before used.

- The product shall be stored in non corrosive gas (Cl<sub>2</sub>, NH<sub>3</sub>, SO<sub>2</sub>, Nox, etc.).

- Any excess mechanical shock including, but not limited to, sticking the packing materials by sharp object and dropping the product, shall not be applied in order not to damage the packing materials.

This product is applicable to MSL3 (Based on IPC/JEDEC J-STD-020)

- After the packing opened, the product shall be stored at <30 °C / <60 %RH and the product shall be used within 168 hours.

- When the color of the indicator in the packing changed, the product shall be baked before soldering.

Baking condition: 125 +5/-0 °C, 24 hours, 1 time

The products shall be baked on the heat-resistant tray because the material (Base Tape, Reel Tape and Cover Tape) are not heat-resistant.

### **13.2 Handling Conditions**

Be careful in handling or transporting products because excessive stress or mechanical shock may break products.

Handle with care if products may have cracks or damages on their terminals, the characteristics of products may change. Do not touch products with bear hands that may result in poor solderability.

### **13.3 Standard PCB Design (Land Pattern and Dimensions)**

All the ground terminals should be connected to the ground patterns. Furthermore, the ground pattern should be provided between IN and OUT terminals. Please refer to the specifications for the standard land dimensions.

The recommended land pattern and dimensions is as Murata's standard. The characteristics of products may vary depending on the pattern drawing method, grounding method, land dimensions, land forming method of the NC terminals and the PCB material and thickness. Therefore, be sure to verify the characteristics in the actual set. When using non-standard lands, contact Murata beforehand.

### **13.4 Notice for Chip Placer :**

When placing products on the PCB, products may be stressed and broken by uneven forces from a worn-out chucking locating claw or a suction nozzle. To prevent products from damages, be sure to follow the specifications for the maintenance of the chip placer being used. For the positioning of products on the PCB, be aware that mechanical chucking may damage products.

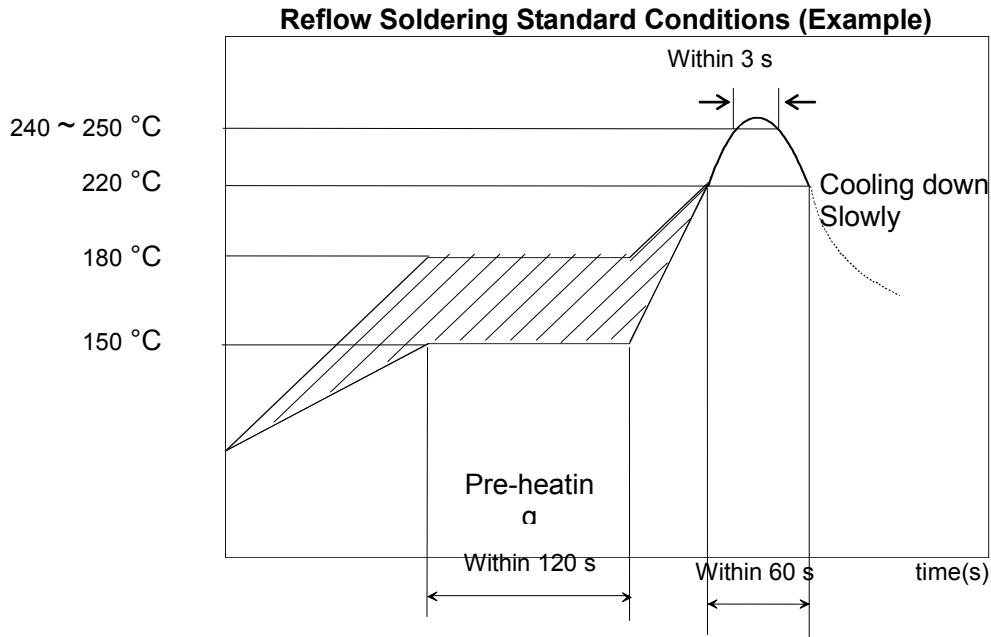
### **13.5 Soldering Conditions :**

The recommendation conditions of soldering are as in the following figure.

When products are immersed in solvent after mounting, pay special attention to maintain the temperature difference within 100 °C. Soldering must be carried out by the above mentioned conditions to prevent products from damage. Set up the highest temperature of reflow within 260 °C.

Contact Murata before use if concerning other soldering conditions.





Please use the reflow within 2 times.

Use rosin type flux or weakly active flux with a chlorine content of 0.2 wt % or less.

### 13.6 Cleaning :

Since this Product is Moisture Sensitive, any cleaning is not permitted.

### 13.7 Operational Environment Conditions :

Products are designed to work for electronic products under normal environmental conditions (ambient temperature, humidity and pressure). Therefore, products have no problems to be used under the similar conditions to the above-mentioned. However, if products are used under the following circumstances, it may damage products and leakage of electricity and abnormal temperature may occur.

- In an atmosphere containing corrosive gas ( Cl<sub>2</sub>, NH<sub>3</sub>, SO<sub>x</sub>, NO<sub>x</sub> etc.).
- In an atmosphere containing combustible and volatile gases.
- Dusty place.
- Direct sunlight place.
- Water splashing place.
- Humid place where water condenses.
- Freezing place.

If there are possibilities for products to be used under the preceding clause, consult with Murata before actual use.

As it might be a cause of degradation or destruction to apply static electricity to products, do not apply static electricity or excessive voltage while assembling and measuring.

### 13.8 Input Power Capacity :

Products shall be used in the input power capacity as specified in this specifications.

Inform Murata beforehand, in case that the components are used beyond such input power capacity range.

## **14. Regulatory Statements**

### **14.1 FCC Statements**

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) This device must accept any interference received, including interference that may cause undesired operation.

Cet appareil est conforme à la section 15 des réglementations de la FCC. Le fonctionnement de l'appareil est sujet aux deux conditions suivantes :

- (1) cet appareil ne doit pas provoquer d'interférences néfastes, et
- (2) cet appareil doit tolérer les interférences reçues, y compris celles qui risquent de provoquer un fonctionnement indésirable.

Note: This product has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This product generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this product does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Please take attention that changes or modification not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

This equipment should be installed and operated with a minimum distance 20cm between the radiator and your body

Cet équipement doit être installé et utilisé à une distance minimale de 20 cm entre le radiateur et votre corps

When the FCC ID is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can be use wording "Contains transmitter module FCC ID: ML6CMABZ" or "Contains FCC ID: ML6CMABZ".

## 14.2 IC Statements

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions:

- (1) this device may not cause interference, and
- (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radioexempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

- (1) l'appareil ne doit pas produire de brouillage, et
- (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

ISED RF exposure statement:

This equipment complies with ISED radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

Le rayonnement de la classe b respecte ISED fixaient un environnement non contrôlés. Installation et mise en œuvre de ce matériel devrait avec échangeur distance minimale entre 20 cm ton corps. Lanceurs ou ne peuvent pas coexister cette antenne ou capteurs avec d'autres.

When the ISED certification number is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can be use wording "Contains transmitter module IC: 3330A-CMABZ" or "Contains IC:3330A-CMABZ".

Lorsque le numéro de certification ISED n'est pas visible lorsque le module est installé dans un autre appareil, l'extérieur de l'appareil dans lequel le module est installé doit également afficher une étiquette faisant référence au module inclus. Cette étiquette extérieure peut être libellée Contient le module émetteur IC:3330A-CMABZ ou Contient IC: 3330A-CMABZ

## 14.3 General Statements

- (1) Dipole Antenna with maximum gain 1.2dBi.

| Ant. | Brand  | Model Name | Antenna Type | Connector | Gain (dBi) | NOTE    |
|------|--------|------------|--------------|-----------|------------|---------|
| 1    | Murata | CMWX1ZZABZ | Dipole       | N/A       | 1.2        | Antenna |

- (2) The Lora module and antenna use the non-SMA Connector Connect.

Two 0 ohm resistors have been strung between the Lora module and the connector.

(L1 and R5 are 0 ohm resistors.)

- (3) The Lora Module is limited to Orbit Irrigation Products, LLC.

 **CAUTION**

PLEASE READ THIS NOTICE BEFORE USING OUR PRODUCTS.

Please make sure that your product has been evaluated and confirmed from the aspect of the fitness for the specifications of our product when our product is mounted to your product.

All the items and parameters in this product specification/datasheet/catalog have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment specified in this specification. You are requested not to use our product deviating from the condition and the environment specified in this specification.

Please note that the only warranty that we provide regarding the products is its conformance to the specifications provided herein. Accordingly, we shall not be responsible for any defects in products or equipment incorporating such products, which are caused under the conditions other than those specified in this specification.

WE HEREBY DISCLAIMS ALL OTHER WARRANTIES REGARDING THE PRODUCTS, EXPRESS OR IMPLIED, INCLUDING WITHOUT LIMITATION ANY WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE, THAT THEY ARE DEFECT-FREE, OR AGAINST INFRINGEMENT OF INTELLECTUAL PROPERTY RIGHTS.

The product shall not be used in any application listed below which requires especially high reliability for the prevention of such defect as may directly cause damage to the third party's life, body or property. You acknowledge and agree that, if you use our products in such applications, we will not be responsible for any failure to meet such requirements.

Furthermore, YOU AGREE TO INDEMNIFY AND DEFEND US AND OUR AFFILIATES AGAINST ALL CLAIMS, DAMAGES, COSTS, AND EXPENSES THAT MAY BE INCURRED, INCLUDING WITHOUT LIMITATION, ATTORNEY FEES AND COSTS, DUE TO THE USE OF OUR PRODUCTS IN SUCH APPLICATIONS.

- Aircraft equipment.
- Aerospace equipment
- Undersea equipment.
- Power plant control equipment
- Medical equipment.
- Transportation equipment (vehicles, trains, ships, elevator, etc.).
- Traffic signal equipment.
- Disaster prevention / crime prevention equipment.
- Burning / explosion control equipment
- Application of similar complexity and/ or reliability requirements to the applications listed in the above.

We expressly prohibit you from analyzing, breaking, Reverse-Engineering, remodeling altering, and reproducing our product. Our product cannot be used for the product which is prohibited from being manufactured, used, and sold by the regulations and laws in the world.

We do not warrant or represent that any license, either express or implied, is granted under any our patent right, copyright, mask work right, or our other intellectual property right relating to any combination, machine, or process in which our products or services are used. Information provided by us regarding third-party products or services does not constitute a license from us to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from us under our patents or other intellectual property.

Please do not use our products, our technical information and other data provided by us for the purpose of developing of mass-destruction weapons and the purpose of military use.

Moreover, you must comply with "foreign exchange and foreign trade law", the "U.S. export administration regulations", etc.

Please note that we may discontinue the manufacture of our products, due to reasons such as end of supply of materials and/or components from our suppliers.

Customer acknowledges that Murata will, if requested by you, conduct a failure analysis for defect or alleged defect of Products only at the level required for consumer grade Products, and thus such analysis may not always be available or be in accordance with your request (for example, in cases where the defect was caused by components in Products supplied to Murata from a third party).

By signing on specification sheet or approval sheet, you acknowledge that you are the legal representative for your company and that you understand and accept the validity of the contents herein. When you are not able to return the signed version of specification sheet or approval sheet within 90 days from receiving date of specification sheet or approval sheet, it shall be deemed to be your consent

on the content of specification sheet or approval sheet.

Customer acknowledges that engineering samples may deviate from specifications and may contain defects due to their development status.

We reject any liability or product warranty for engineering samples.

In particular we disclaim liability for damages caused by

- the use of the engineering sample other than for evaluation purposes, particularly the installation or integration in the product to be sold by you,
- deviation or lapse in function of engineering sample,
- improper use of engineering samples.

We disclaims any liability for consequential and incidental damages.

If you can't agree the above contents, you should inquire our sales.